

# LBTN180Y3T1G

## S-LBTN180Y3T1G

NPN power transistors

### 1. FEATURES

- High current
- High power dissipation capability
- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.

### 2. APPLICATIONS

- Linear voltage regulators
- Low-side switches
- Battery-driven devices
- Power management
- MOSFET drivers
- Amplifiers

### 3. DEVICE MARKING AND ORDERING INFORMATION

| Device       | Marking | Shipping       |
|--------------|---------|----------------|
| LBTN180Y3T1G | B       | 1000/Tape&Reel |

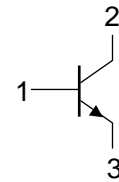
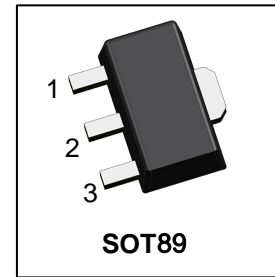
### 4. MAXIMUM RATINGS(Ta = 25°C)

| Parameter                       | Symbol | Limits | Unit |
|---------------------------------|--------|--------|------|
| Collector–Emitter Voltage       | VCEO   | 80     | V    |
| Collector–Base Voltage          | VCBO   | 100    | V    |
| Emitter–Base Voltage            | VEBO   | 5      | V    |
| Collector Current               | IC     | 1      | A    |
| Peak collector current(tp≤1 ms) | ICM    | 2      | A    |
| Base current                    | IB     | 0.3    | A    |
| Peak base current(tp≤1 ms)      | IBM    | 0.3    | A    |

### 5. THERMAL CHARACTERISTICS

| Parameter  | Symbol  | Limits   | Unit  |
|--|---------|----------|-------|
| Total Device Dissipation,<br>FR-4 Board (Note 1) @ TA = 25°C | PD      | 550      | mW    |
| Derate above 25°C  |         | 4.4      | mW/°C |
| Thermal Resistance,<br>Junction–to–Ambient                   | RθJA    | 225      | °C/W  |
| Junction–to–Case   | RθJC    | 50       | °C/W  |
| Junction and Storage temperature                             | TJ,Tstg | -65~+150 | °C    |

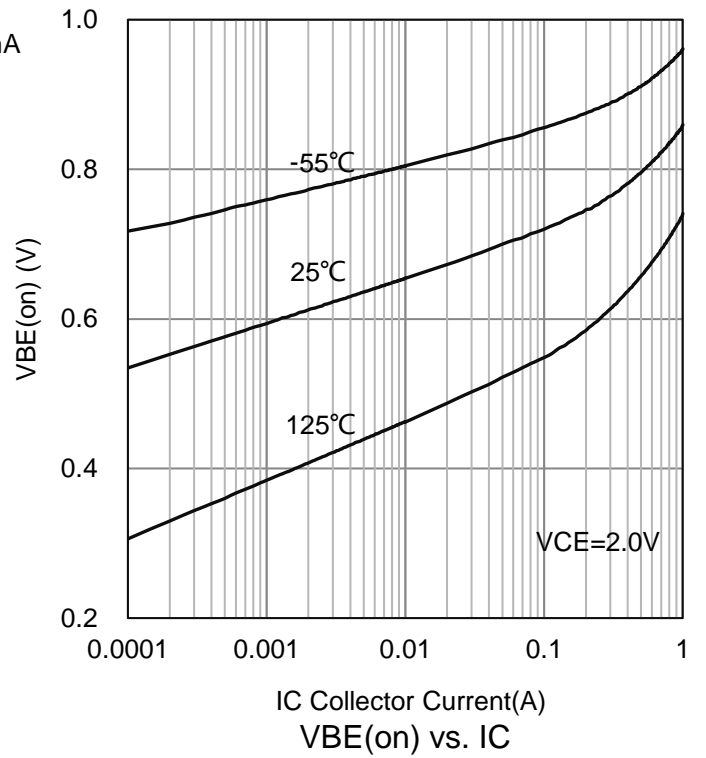
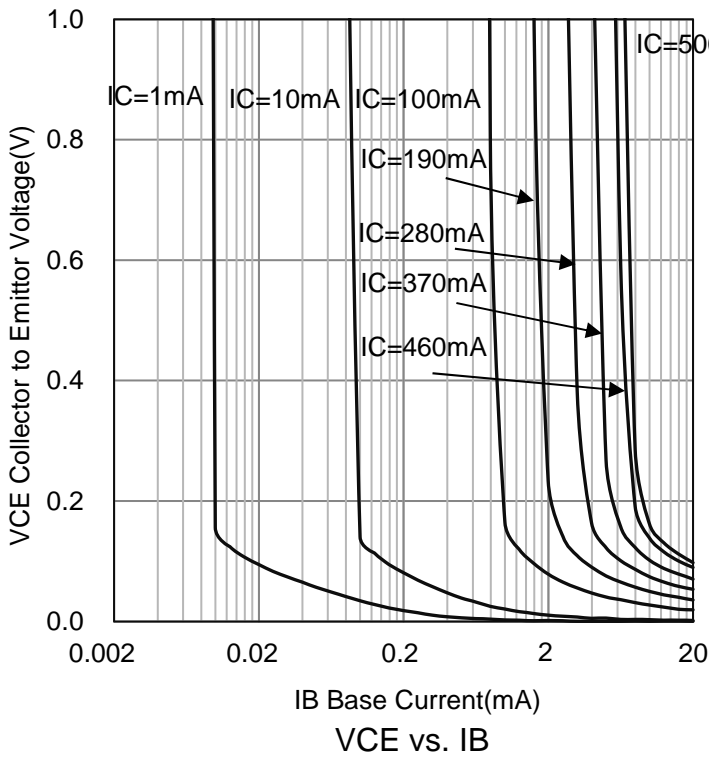
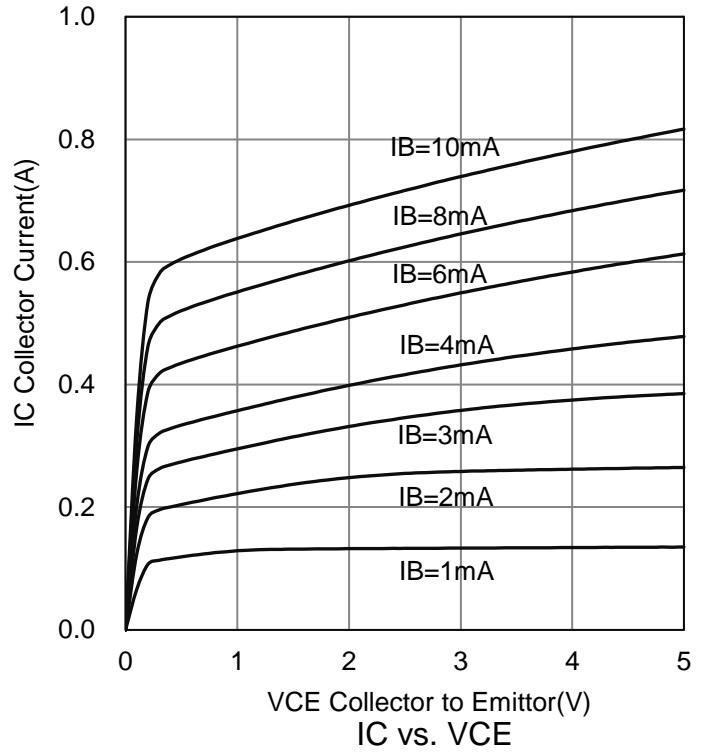
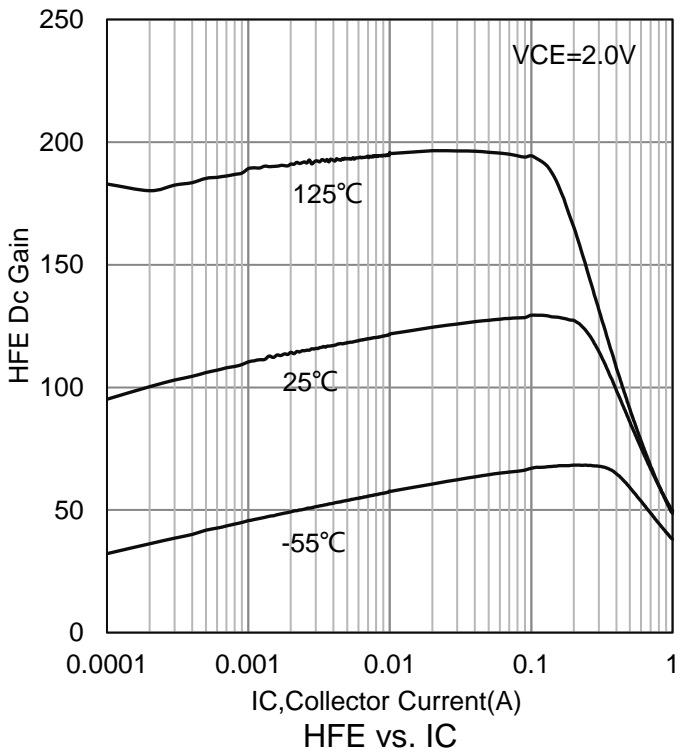
1.PCB Size:30.0mm×25.0mm×1.6mm,FR-4 Board;



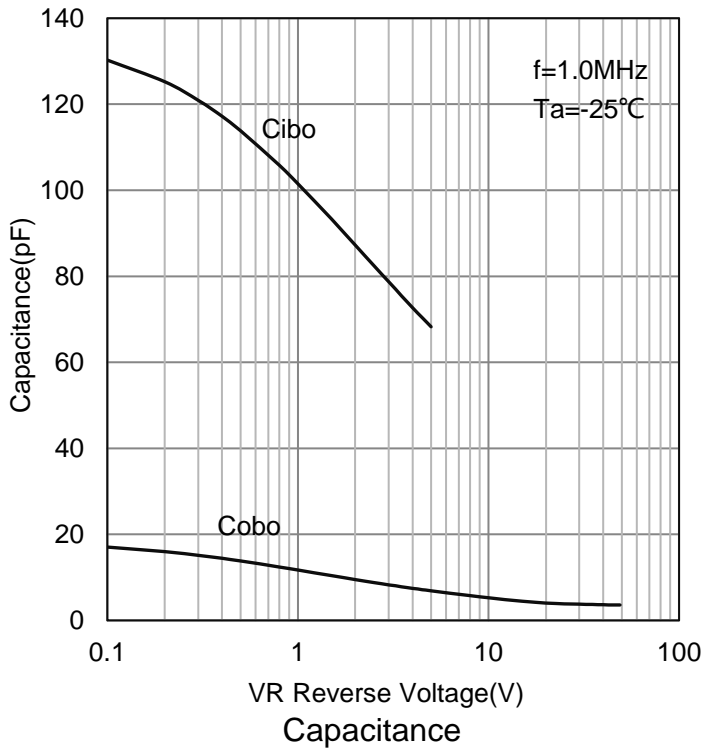
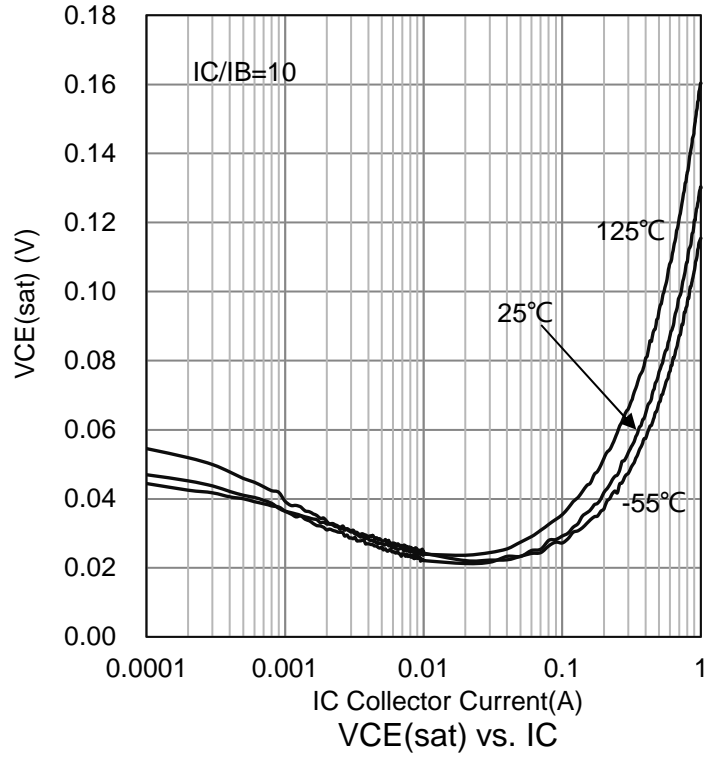
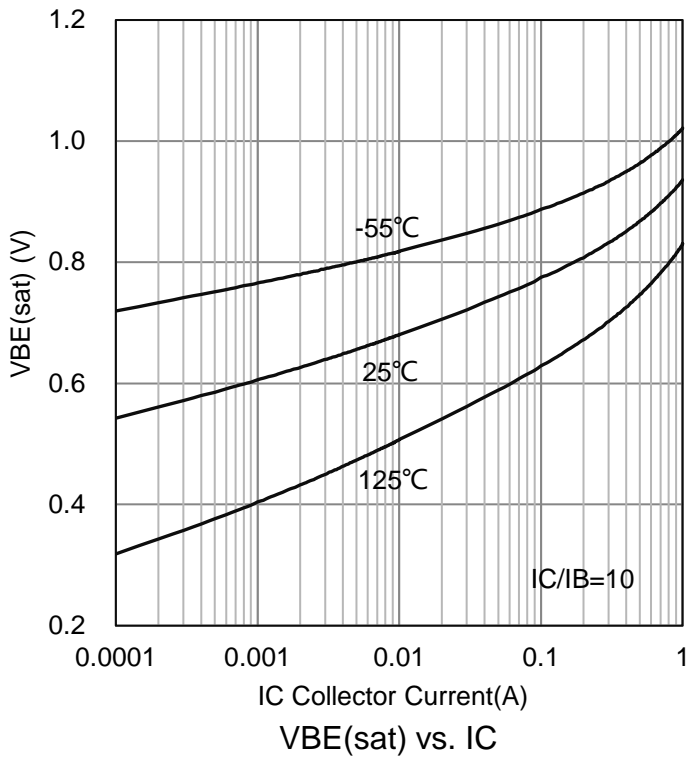
**6. ELECTRICAL CHARACTERISTICS (Ta= 25°C)**

| Characteristic  | Symbol   | Min.            | Typ.        | Max.          | Unit     |
|---|----------|-----------------|-------------|---------------|----------|
| Collector–Emitter Breakdown Voltage<br>(IC = 1 mA, IB = 0)  | VBR(CEO) | 80              | -           | -             | V        |
| Collector–Base Breakdown Voltage<br>(IC = 100 µA, IE = 0)   | VBR(CBO) | 100             | -           | -             | V        |
| Emitter–Base Breakdown Voltage<br>(IE = 100 µA, IC = 0)   | VBR(EBO) | 5               | -           | -             | V        |
| Collector Cutoff Current<br>(VCB = 30 V, IE = 0 A)<br>(VCB = 30 V, IE = 0 A, Tj = 150°C)          | ICBO     | -               | -           | 100<br>10     | nA<br>µA |
| Emitter Cut-off Current<br>(VEB = 5V, IC = 0)   | IEBO     | -               | -           | 100           | nA       |
| Collector-Emitter cutoff Current<br>(VCE = 80V, IB = 0)   | ICEO     | -               | -           | 10            | µA       |
| DC Current Gain<br>(VCE = 2 V, IC = 5 mA)<br>(VCE = 2 V, IC = 150 mA)<br>(VCE = 2 V, IC = 500 mA) | HFE      | 63<br>100<br>45 | -<br>-<br>- | -<br>250<br>- |          |
| Collector–Emitter Saturation Voltage<br>(IC = 500 mA, IB = 50 mA)                                 | VCE(sat) | -               | -           | 0.5           | V        |
| Base-Emitter voltage<br>(VCE = 2 V, IC = 500 mA)  | VBE      | -               | -           | 1             | V        |
| Transition Frequency<br>(VCE = 5 V, IC = 50 mA, f = 100 MHz)                                      | fT       | 100             | 180         | -             | MHz      |
| Collector Capacitance<br>(VCB = 10 V, IE = ie = 0 A, f = 1 MHz)                                   | Cc       | -               | 6           | -             | pF       |

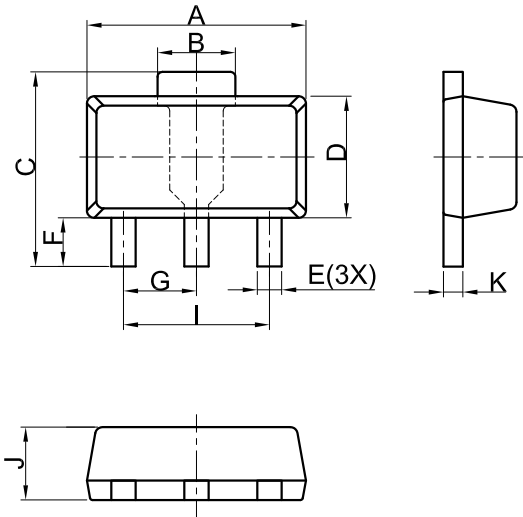
**7.ELECTRICAL CHARACTERISTICS CURVES**



7.ELECTRICAL CHARACTERISTICS CURVES(Con.)



### 8.OUTLINE AND DIMENSIONS

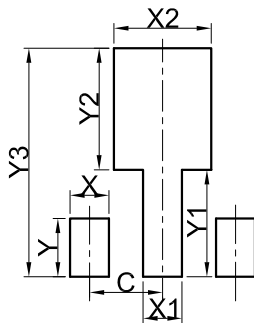


| SOT89                |          |      |      |
|----------------------|----------|------|------|
| DIM                  | MIN      | NOR  | MAX  |
| A                    | 4.30     | 4.50 | 4.70 |
| B                    | 1.40     | 1.60 | 1.80 |
| C                    | 3.90     | 4.00 | 4.25 |
| D                    | 2.30     | 2.50 | 2.70 |
| E                    | 0.40     | 0.50 | 0.58 |
| F                    | 0.90     | 1.00 | 1.20 |
| G                    | 1.50 BSC |      |      |
| I                    | 3.00 BSC |      |      |
| J                    | 1.40     | 1.50 | 1.60 |
| K                    | 0.34     | 0.40 | 0.50 |
| All Dimensions in mm |          |      |      |

#### GENERAL NOTES

1. Top package surface finish Ra0.4±0.2um
2. Bottom package surface finish Ra0.7±0.2um
3. Side package surface finish Ra0.4±0.2um
4. Protrusion or Gate Burrs shall not exceed 0.10mm per side.

### 9.SOLDERING FOOTPRINT



| SOT89 |      |
|-------|------|
| DIM   | (mm) |
| X     | 0.80 |
| Y     | 1.20 |
| X1    | 0.80 |
| Y1    | 2.20 |
| X2    | 2.00 |
| Y2    | 2.50 |
| C     | 1.50 |
| Y3    | 4.70 |

## **DISCLAIMER**

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